



MATERIAL DECLARATION DATA SHEET

Device Name	Package Type	Pkg Wt (g)			
M2GL010	FG484(23x23mm)	2.34			
Material Breakdown of Component	Material Breakdown (%)	Substance Name	CAS No.	Weight (g)	Substance Mass (%)
MOLD COMPOUND	40.24	Silica	60676-86-0	0.8728	92.7
		Resin	Proprietary	0.0471	5
		Metal Hydroxide	Proprietary	0.0188	2
		Carbon Black	1333-86-4	0.0028	0.3
				0.94157	100
SUBSTRATE	35.34	Bismaleimide/Triazine	13676-54-5	0.5429	65.65
		Copper (Cu)	7440-50-8	0.2642	31.95
		Gold (Au)	7440-57-5	0.0032	0.385
		Nickel (Ni)	7440-02-0	0.0167	2.015
				0.8270	100
DIE	0.88	Silicon	7440-21-3	0.0207	100
				0.0207	100
DIE ATTACH EPOXY	0.13	Silver	7440-22-4	0.0024	76
		Epoxy Resin	Proprietary	0.0008	24
				0.0031	100
SOLDER BALL	21.88	Tin	7440-31-5	0.3226	63
		Lead	7439-92-1	0.1895	37
				0.5121	100
GOLD WIRE	1.52	Gold	7440-57-5	0.0355	99.99
		Doping	Proprietary	0.0000	0.01
				0.0355	100
				2.3400	

Disclaimer: Microsemi believes this information to be correct, but cannot guarantee its completeness or accuracy. The information is based on data received from sources outside our company.

Revision No.	Date	Description of Change
	2/12/2014	Original release